

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (original): A mounting substrate, comprising:

a substrate body having at least first and second adjacent chip mounting regions defined on a surface thereof, and further having a dicing line defined between the first and second mounting regions;

a first plurality of inner electrodes aligned along a first side of the first chip mounting region;

a second plurality of inner electrodes aligned along a second side of the second chip mounting region, wherein the first side of the first chip mounting region confronts the second side of the second chip mounting region; and

an interconnect wiring pattern located between the first and second chip mounting region, and commonly connected to the first plurality of inner electrodes and the second plurality of inner electrodes, wherein the interconnect wiring pattern includes a plurality of connected wiring portions, and wherein at least some of said wiring pattern extend obliquely across the dicing line.

Claim 2 (currently amended): The mounting substrate according to claim 1, and wherein

[[oher]] other wiring patterns of the interconnect wiring pattern extend at right ~~angle~~
angles across the dicing line.

Claim 3 (original): The mounting substrate according to claim 1, wherein the
interconnecting wiring pattern has a zigzag configuration.

Claim 4 (canceled)

Claim 5 (canceled)